

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1744	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L2	56	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L3	8	((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L4	1166	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L5	286	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L6	49	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L7	6	((((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L8	79	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L9	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L10	35	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47

L11	13	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L12	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L13	26	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L14	921	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L15	847	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L16	45	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L17	109	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L18	318	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L19	322	signal with line and ground with line and 438/6\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L20	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:47
L21	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:47

L22	234	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L23	147	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L24	402	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L25	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/11/09 13:47
L26	214	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L27	2541	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L28	1430	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L29	723	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L30	94	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L31	100	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L32	1597	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47

L33	829	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L34	171	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L35	4995	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L36	410	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L37	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L38	701	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L39	440	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L40	97	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L41	1087	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L42	679	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47

L43	520	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L44	4	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L45	477	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L46	237	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L47	198	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L48	88	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L49	1604	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L50	976	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L51	644	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L52	578	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47

L53	6	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L54	184	(((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L55	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L56	11329	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L57	114	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L58	7848	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L59	3646	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L60	203	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L61	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:47
L62	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/11/09 13:47
L63	32	"5903053".URPN.	USPAT	OR	ON	2005/11/09 13:47
L64	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:47
L65	6	"5705857".URPN.	USPAT	OR	ON	2005/11/09 13:47
L66	15	"5429978".URPN.	USPAT	OR	ON	2005/11/09 13:47

L67	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/11/09 13:47
L68	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L69	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/11/09 13:47
L70	29	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L71	24	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L72	22	"5909044".URPN.	USPAT	OR	ON	2005/11/09 13:47
L73	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L74	12	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L75	1079	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L76	409	waveguide with trench	USPAT	OR	ON	2005/11/09 13:47
L77	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/11/09 13:47
L78	3	"5783844".URPN.	USPAT	OR	ON	2005/11/09 13:47
L79	124	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/11/09 13:47
L80	196	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/11/09 13:47
L81	91	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/11/09 13:47

L82	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/11/09 13:47
L83	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/11/09 13:47
L84	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/11/09 13:47
L85	194	gate with polysilicon with copper	USPAT	OR	ON	2005/11/09 13:47
L86	3992	silicide with silicon with nitride	USPAT	OR	ON	2005/11/09 13:47
L87	2179	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:47
L88	996	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/11/09 13:47
L89	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/11/09 13:47
L90	3	silicide with spacer with copper	USPAT	OR	ON	2005/11/09 13:47
L91	0	silicide with copper and sinane	USPAT	OR	ON	2005/11/09 13:47
L92	302	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:47
L93	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/11/09 13:47
L94	24	copper with silicide and 438/655.ccls.	USPAT	OR	ON	2005/11/09 13:47
L95	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/11/09 13:47
L96	1	"5,447,887".pn.	USPAT	OR	ON	2005/11/09 13:47
L97	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:47
L98	526	thermal with evaporation with CVD	USPAT	OR	ON	2005/11/09 13:47
L99	186	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:47
L100	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:47
L101	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:47
L102	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/11/09 13:47
L103	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:47
L104	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/11/09 13:47
L105	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/11/09 13:47
L106	10	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/11/09 13:47
L107	24	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:47
L108	144	trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:47
L109	894	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/11/09 13:47
L110	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/11/09 13:47

L111	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/11/09 13:47
L112	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/11/09 13:47
L113	195	trench with etch\$5 with commonly	USPAT	OR	ON	2005/11/09 13:47
L114	1	"4631803".pn.	USPAT	OR	ON	2005/11/09 13:47
L115	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L116	796	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L117	165	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L118	260	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L119	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/11/09 13:47
L120	23	"5424693".URPN.	USPAT	OR	ON	2005/11/09 13:47
L121	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/11/09 13:47
L122	991	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:47
L123	201	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L124	176	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:47
L125	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/11/09 13:47
L126	8	"5652557".URPN.	USPAT	OR	ON	2005/11/09 13:47

L127	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/11/09 13:47
L128	27	"5426399".URPN.	USPAT	OR	ON	2005/11/09 13:47
L129	4	"4607240".URPN.	USPAT	OR	ON	2005/11/09 13:48
L130	410	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L131	31	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L132	292	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L133	261	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L134	146	((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L135	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L136	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L137	9	"3975690".URPN.	USPAT	OR	ON	2005/11/09 13:48
L138	5	"4322695".URPN.	USPAT	OR	ON	2005/11/09 13:48
L139	5	"5519363".URPN.	USPAT	OR	ON	2005/11/09 13:48
L140	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/11/09 13:48
L141	1226	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48

L142	236	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L143	221	((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L144	201	((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246). CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L145	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:48
L146	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/11/09 13:48
L147	15	"4379307".URPN.	USPAT	OR	ON	2005/11/09 13:48
L148	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/11/09 13:48
L149	4	"5512776".URPN.	USPAT	OR	ON	2005/11/09 13:48
L150	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/11/09 13:48
L151	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:48
L152	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:48
L153	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/11/09 13:48
L154	18921	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L155	575	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L156	296	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L157	2468	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L158	1036	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L159	1014	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L160	21413	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L161	53	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L162	10	"4554567".URPN.	USPAT	OR	ON	2005/11/09 13:48
L163	623	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L164	1269361	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L165	9	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L166	537	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L167	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:48
L168	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/11/09 13:48
L169	30	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L170	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L171	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L172	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L173	1413	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L174	506	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L175	757	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L176	1186	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L177	3	(L172 or L173 or L175 or L176 or L174) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L178	0	(L172 or L173 or L175 or L176 or L174) and transmsion adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L179	25	(L172 or L173 or L175 or L176 or L174) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L180	1744	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L181	1166	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L182	286	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L183	49	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L184	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L185	921	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L186	847	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L187	2541	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L188	1430	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L189	723	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L190	1597	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L191	829	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L192	4995	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L193	1087	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L194	679	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L195	520	((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L196	477	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L197	198	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L198	1604	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L199	976	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L200	644	((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L201	578	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L202	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L203	11329	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L204	7848	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L205	3646	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L206	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L207	24	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L208	196	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/11/09 13:48
L209	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/11/09 13:48
L210	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/11/09 13:48
L211	3992	silicide with silicon with nitride	USPAT	OR	ON	2005/11/09 13:48
L212	2179	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:48
L213	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/11/09 13:48
L214	0	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:48
L215	302	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:48
L216	526	thermal with evaporation with CVD	USPAT	OR	ON	2005/11/09 13:48
L217	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:48
L218	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/11/09 13:48
L219	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/11/09 13:48
L220	894	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/11/09 13:48
L221	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/11/09 13:48

L222	796	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L223	991	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L224	201	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L225	410	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L226	261	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L227	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L228	1226	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L229	236	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L230	221	((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L231	18921	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L232	575	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L233	2468	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L234	1036	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L235	1014	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L236	21413	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L237	623	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L238	1269361	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON AJD OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L239	30	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L240	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L241	1413	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L242	506	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L243	.757	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48

L244	1186	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:48
L245	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L246	3	(L245 or L241 or L243 or L244 or L242) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L247	0	(L245 or L241 or L243 or L244 or L242) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L248	1	"5,447,887".pn.	USPAT	OR	ON	2005/11/09 13:48
L249	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:48
L250	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:48
L251	1	"4631803".pn.	USPAT	OR	ON	2005/11/09 13:48
L252	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L253	56	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L254	8	((((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L255	6	((((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and (((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and (((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L256	79	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48

L257	35	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L258	13	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L259	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L260	26	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L261	45	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:48
L262	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:48
L263	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:48
L264	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/11/09 13:48
L265	94	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L266	100	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L267	97	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49

L268	4	(((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L269	88	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L270	6	((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L271	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:49
L272	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/11/09 13:49
L273	32	"5903053".URPN.	USPAT	OR	ON	2005/11/09 13:49
L274	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:49
L275	6	"5705857".URPN.	USPAT	OR	ON	2005/11/09 13:49
L276	15	"5429978".URPN.	USPAT	OR	ON	2005/11/09 13:49
L277	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/11/09 13:49
L278	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/11/09 13:49
L279	29	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L280	22	"5909044".URPN.	USPAT	OR	ON	2005/11/09 13:49
L281	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L282	12	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49

L283	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/11/09 13:49
L284	3	"5783844".URPN.	USPAT	OR	ON	2005/11/09 13:49
L285	91	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/11/09 13:49
L286	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/11/09 13:49
L287	3	silicide with spacer with copper	USPAT	OR	ON	2005/11/09 13:49
L288	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/11/09 13:49
L289	24	copper with silicide and 438/655. ccls.	USPAT	OR	ON	2005/11/09 13:49
L290	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/11/09 13:49
L291	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:49
L292	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/11/09 13:49
L293	10	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/11/09 13:49
L294	24	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:49
L295	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/11/09 13:49
L296	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/11/09 13:49
L297	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L298	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/11/09 13:49
L299	23	"5424693".URPN.	USPAT	OR	ON	2005/11/09 13:49
L300	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/11/09 13:49
L301	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/11/09 13:49
L302	8	"5652557".URPN.	USPAT	OR	ON	2005/11/09 13:49
L303	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/11/09 13:49
L304	27	"5426399".URPN.	USPAT	OR	ON	2005/11/09 13:49
L305	4	"4607240".URPN.	USPAT	OR	ON	2005/11/09 13:49

L306	31	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L307	9	"3975690".URPN.	USPAT	OR	ON	2005/11/09 13:49
L308	5	"4322695".URPN.	USPAT	OR	ON	2005/11/09 13:49
L309	5	"5519363".URPN.	USPAT	OR	ON	2005/11/09 13:49
L310	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/11/09 13:49
L311	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:49
L312	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/11/09 13:49
L313	15	"4379307".URPN.	USPAT	OR	ON	2005/11/09 13:49
L314	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/11/09 13:49
L315	4	"5512776".URPN.	USPAT	OR	ON	2005/11/09 13:49
L316	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/11/09 13:49
L317	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:49
L318	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:49
L319	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/11/09 13:49
L320	53	((("257"\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L321	10	"4554567".URPN.	USPAT	OR	ON	2005/11/09 13:49
L322	9	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L323	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:49
L324	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/11/09 13:49
L325	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49

L326	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L327	25	(L245 or L241 or L243 or L244 or L242) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L328	109	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L329	147	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L330	171	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L331	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L332	184	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L333	114	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L334	203	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L335	124	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/11/09 13:49
L336	194	gate with polysilicon with copper	USPAT	OR	ON	2005/11/09 13:49
L337	186	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:49
L338	144	trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:49
L339	195	trench with etch\$5 with commonly	USPAT	OR	ON	2005/11/09 13:49

L340	165	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L341	176	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L342	146	((((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L343	201	(((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L344	234	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L345	214	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L346	237	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L347	260	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L348	292	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L349	296	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L350	318	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49

L351	322	signal with line and ground with line and 438/6\$2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L352	402	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L353	410	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L354	409	waveguide with trench	USPAT	OR	ON	2005/11/09 13:49
L355	440	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L356	537	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L357	701	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L358	996	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/11/09 13:49
L359	1079	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L360	2	"6756673".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L361	22	("4575700" "5426399" "5429978" "5447887" "5849625" "5986331" "6140688" "6255698" "6259407" "6407441" "6756673").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L362	1226	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49

L363	2615	coplanar with waveguide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L364	77	L362 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L365	1413	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L366	1186	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L367	2	L365 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L368	3	L363 and L366	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L369	757	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L370	1	L369 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L371	991	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49

L372	85	L371 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L373	410	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L374	12	L373 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L375	731	(361/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L376	0	L375 and L363	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L377	1744	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L378	1166	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L379	286	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L380	49	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L381	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49

L382	921	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L383	847	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L384	2541	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L385	1430	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L386	723	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L387	1597	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L388	829	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L389	4995	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:49
L390	1087	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:49
L391	679	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L392	520	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L393	477	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L394	198	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L395	1604	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L396	976	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L397	644	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L398	578	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L399	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L400	11329	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L401	7848	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L402	3646	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L403	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L404	24	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L405	196	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/11/09 13:50
L406	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/11/09 13:50
L407	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/11/09 13:50
L408	3992	silicide with silicon with nitride	USPAT	OR	ON	2005/11/09 13:50
L409	2179	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:50
L410	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/11/09 13:50
L411	0	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:50
L412	302	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:50
L413	526	thermal with evaporation with CVD	USPAT	OR	ON	2005/11/09 13:50
L414	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:50
L415	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/11/09 13:50
L416	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/11/09 13:50
L417	894	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/11/09 13:50
L418	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/11/09 13:50
L419	796	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L420	991	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50

L421	201	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L422	410	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L423	261	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L424	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L425	1226	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L426	236	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L427	221	((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L428	18921	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L429	575	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L430	2468	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L431	1036	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L432	1014	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L433	21413	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L434	623	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L435	1269361	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L436	30	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L437	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L438	1413	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L439	506	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L440	757	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L441	1186	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L442	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L443	3	(L442 or L438 or L440 or L441 or L439) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L444	0	(L442 or L438 or L440 or L441 or L439) and transmsion adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L445	1744	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L446	1166	signal with line and ground with line and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L447	286	(signal with line and ground with line and "438"/\$.ccls.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L448	49	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L449	4	signal with ground with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L450	921	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L451	847	((438/627).CCLS.) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L452	2541	coplanar with waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L453	1430	(coplanar with waveguide) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L454	723	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L455	1597	forbes and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L456	829	forbes and ahn and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L457	4995	waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L458	1087	(438/653).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L459	679	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L460	520	((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L461	477	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L462	198	(438/665).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50

L463	1604	(438/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L464	976	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L465	644	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L466	578	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L467	0	isolation with trench and silicon with substrate with "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L468	11329	isolation with trench and silicon with substrate and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L469	7848	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L470	3646	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L471	0	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L472	24	copper with gate same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L473	196	silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide	USPAT	OR	ON	2005/11/09 13:50

L474	0	gate with polysilicon with copper with cost	USPAT	OR	ON	2005/11/09 13:50
L475	1	gate with polysilicon with copper with improve	USPAT	OR	ON	2005/11/09 13:50
L476	3992	silicide with silicon with nitride	USPAT	OR	ON	2005/11/09 13:50
L477	2179	silicide with silicon with nitride and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:50
L478	1	silicide with spacer with copper with gate	USPAT	OR	ON	2005/11/09 13:50
L479	0	silicide with copper and sinane	USPAT	OR	ON	2005/11/09 13:50
L480	302	silicide with copper and silane	USPAT	OR	ON	2005/11/09 13:50
L481	526	thermal with evaporation with CVD	USPAT	OR	ON	2005/11/09 13:50
L482	53	thermal with thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:50
L483	0	thermal adj evaporation with CVD with (cost improve)	USPAT	OR	ON	2005/11/09 13:50
L484	1	isolation with trench with etch with cost	USPAT	OR	ON	2005/11/09 13:50
L485	894	trench with etch\$5 with oxidation	USPAT	OR	ON	2005/11/09 13:50
L486	1	trench with etch\$5 with oxidation with cost	USPAT	OR	ON	2005/11/09 13:50
L487	796	coplanar with line and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L488	991	(333/246).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L489	201	((333/246).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L490	410	(333/1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:50
L491	261	((333/246).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50

L492	0	JP-2000232212.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:50
L493	1226	(333/238).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:51
L494	236	((333/238).CCLS.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L495	221	(((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L496	18921	ahn.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L497	575	(kie with ahn).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L498	2468	"257"/\$.CCLS. AND TRANSMISSION ADJ LINE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L499	1036	("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L500	1014	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L501	21413	(((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L502	623	TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L503	1269361	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON AJD OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51

L504	30	"5426399"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L505	0	"5426399.pn."	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L506	1413	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:51
L507	506	(257/752).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:51
L508	757	(257/754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:51
L509	1186	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:51
L510	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L511	3	(L510 or L506 or L508 or L509 or L507) and wave with guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L512	0	(L510 or L506 or L508 or L509 or L507) and transmsion adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L513	1	"5,447,887".pn.	USPAT	OR	ON	2005/11/09 13:51
L514	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:51
L515	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:51
L516	1	"4631803".pn.	USPAT	OR	ON	2005/11/09 13:51

L517	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L518	1	"5,447,887".pn.	USPAT	OR	ON	2005/11/09 13:51
L519	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:51
L520	1	"6255698".pn.	USPAT	OR	ON	2005/11/09 13:51
L521	1	"4631803".pn.	USPAT	OR	ON	2005/11/09 13:51
L522	1	1999jp-0196348.AP,PRAI.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L523	56	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L524	8	((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L525	6	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L526	79	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L527	35	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L528	13	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L529	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51

L530	26	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L531	45	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L532	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:51
L533	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:51
L534	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/11/09 13:51
L535	94	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L536	100	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L537	97	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L538	4	((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L539	88	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L540	6	((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51

L541	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:51
L542	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/11/09 13:51
L543	32	"5903053".URPN.	USPAT	OR	ON	2005/11/09 13:51
L544	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:51
L545	6	"5705857".URPN.	USPAT	OR	ON	2005/11/09 13:51
L546	15	"5429978".URPN.	USPAT	OR	ON	2005/11/09 13:51
L547	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/11/09 13:51
L548	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/11/09 13:51
L549	29	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L550	22	"5909044".URPN.	USPAT	OR	ON	2005/11/09 13:51
L551	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L552	12	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L553	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/11/09 13:51
L554	3	"5783844".URPN.	USPAT	OR	ON	2005/11/09 13:51
L555	91	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/11/09 13:51
L556	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/11/09 13:51
L557	3	silicide with spacer with copper	USPAT	OR	ON	2005/11/09 13:51
L558	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/11/09 13:51

L559	24	copper with silicide and 438/655. ccls.	USPAT	OR	ON	2005/11/09 13:51
L560	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/11/09 13:51
L561	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:51
L562	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/11/09 13:51
L563	10	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/11/09 13:51
L564	24	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:51
L565	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/11/09 13:51
L566	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/11/09 13:51
L567	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L568	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/11/09 13:51
L569	23	"5424693".URPN.	USPAT	OR	ON	2005/11/09 13:51
L570	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/11/09 13:51
L571	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/11/09 13:51
L572	8	"5652557".URPN.	USPAT	OR	ON	2005/11/09 13:51
L573	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/11/09 13:51
L574	27	"5426399".URPN.	USPAT	OR	ON	2005/11/09 13:51
L575	4	"4607240".URPN.	USPAT	OR	ON	2005/11/09 13:51
L576	31	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L577	9	"3975690".URPN.	USPAT	OR	ON	2005/11/09 13:51
L578	5	"4322695".URPN.	USPAT	OR	ON	2005/11/09 13:51
L579	5	"5519363".URPN.	USPAT	OR	ON	2005/11/09 13:51
L580	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/11/09 13:51
L581	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:51

L582	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/11/09 13:51
L583	15	"4379307".URPN.	USPAT	OR	ON	2005/11/09 13:51
L584	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/11/09 13:51
L585	4	"5512776".URPN.	USPAT	OR	ON	2005/11/09 13:51
L586	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/11/09 13:51
L587	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:51
L588	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:51
L589	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/11/09 13:51
L590	53	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:51
L591	10	"4554567".URPN.	USPAT	OR	ON	2005/11/09 13:52
L592	9	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L593	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:52
L594	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/11/09 13:52
L595	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L596	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L597	25	(L442 or L438 or L440 or L441 or L439) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L598	56	((438/427).CCLS.) and oxide and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52

L599	8	((438/427).CCLS.) and oxide and silicide) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L600	6	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and evaporation) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide) and ((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L601	79	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L602	35	((signal with line and ground with line and "438"/\$.ccls.) and barrier) and silane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L603	13	signal with ground same trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L604	3	((438/427).CCLS.) and metal with line and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L605	26	((438/427).CCLS.) and metal with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L606	45	((438/627).CCLS.) and barrier) and ((438/627).CCLS.) and evaporation) and ((438/627).CCLS.) and silicide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L607	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:52
L608	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:52
L609	7	("3616282" "5032220" "5121237" "5617493" "5834055" "5895742" "5959765").PN.	USPAT	OR	ON	2005/11/09 13:52

L610	94	((coplanar with waveguide) and signal and ground) and substrate with (trench hole via gap through)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L611	100	waveguide and micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L612	97	substrate with trench and barrier and signal and ground and silicon and oxide and silane and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L613	4	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L614	88	((438/665).CCLS.) and substrate with (trench gap via cavity through hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L615	6	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and ground same signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L616	14	("4252862" "5277985" "5539256" "5595937" "5705857" "5719447" "5744394" "5903053" "5909635" "5976986" "6010966" "6033986" "6054380" "6080529").PN.	USPAT	OR	ON	2005/11/09 13:52
L617	5	("5516579" "5525837" "5607722" "5641985" "5659057").PN.	USPAT	OR	ON	2005/11/09 13:52
L618	32	"5903053".URPN.	USPAT	OR	ON	2005/11/09 13:52
L619	9	("4394223" "4810332" "5071518" "5132775" "5272376" "5298687" "5326412" "5382447" "5545927").PN.	USPAT	OR	ON	2005/11/09 13:52
L620	6	"5705857".URPN.	USPAT	OR	ON	2005/11/09 13:52
L621	15	"5429978".URPN.	USPAT	OR	ON	2005/11/09 13:52
L622	17	("4894696" "4988637" "5026659" "5065273" "5214603" "5292678" "5336629" "5343354" "5348905" "5378907" "5384277" "5389559" "5395786" "5429978" "5661057" "5670805" "5753526").PN.	USPAT	OR	ON	2005/11/09 13:52
L623	5	("5208175" "5372963" "5534455" "5547884" "5589412").PN.	USPAT	OR	ON	2005/11/09 13:52

L624	29	copper with isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L625	22	"5909044".URPN.	USPAT	OR	ON	2005/11/09 13:52
L626	7	copper with ground and isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L627	12	copper with line same isolation with trench and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L628	3	("3425879" "5094973" "5104824").PN.	USPAT	OR	ON	2005/11/09 13:52
L629	3	"5783844".URPN.	USPAT	OR	ON	2005/11/09 13:52
L630	91	(silicon with substrate and oxide with substrate and barrier with oxide and barrier with metal and metal with copper and etch and silicide) and trench	USPAT	OR	ON	2005/11/09 13:52
L631	2	gate with polysilicon with copper same high with temperature	USPAT	OR	ON	2005/11/09 13:52
L632	3	silicide with spacer with copper	USPAT	OR	ON	2005/11/09 13:52
L633	11	silicide with copper and silane and copper with evaporation	USPAT	OR	ON	2005/11/09 13:52
L634	24	copper with silicide and 438/655.ccls.	USPAT	OR	ON	2005/11/09 13:52
L635	45	copper with silicide with nitride with adhesion	USPAT	OR	ON	2005/11/09 13:52
L636	53	thermal adj evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:52
L637	79	isolation with trench with etch with rate	USPAT	OR	ON	2005/11/09 13:52
L638	10	isolation with trench with etch\$5 with cost	USPAT	OR	ON	2005/11/09 13:52
L639	24	isolation with trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:52
L640	13	trench with etch\$5 with oxidation with improve	USPAT	OR	ON	2005/11/09 13:52
L641	3	trench with etch\$5 with oxidation with preferable	USPAT	OR	ON	2005/11/09 13:52
L642	4	("5447887" "6140688").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52

L643	7	("5087896" "5307237" "5424693" "5545924" "5877560" "5952719" "6163458").PN.	USPAT	OR	ON	2005/11/09 13:52
L644	23	"5424693".URPN.	USPAT	OR	ON	2005/11/09 13:52
L645	3	("5294897" "5424693" "5832598").PN.	USPAT	OR	ON	2005/11/09 13:52
L646	8	("4494083" "4816791" "5036301" "5057798" "5229727" "5401912" "5414222" "5757252").PN.	USPAT	OR	ON	2005/11/09 13:52
L647	8	"5652557".URPN.	USPAT	OR	ON	2005/11/09 13:52
L648	8	("3225351" "4482873" "4607240" "4673904" "4772864" "4918049" "5304959" "5426399").PN.	USPAT	OR	ON	2005/11/09 13:52
L649	27	"5426399".URPN.	USPAT	OR	ON	2005/11/09 13:52
L650	4	"4607240".URPN.	USPAT	OR	ON	2005/11/09 13:52
L651	31	((333/1).CCLS.) and coplanar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:52
L652	9	"3975690".URPN.	USPAT	OR	ON	2005/11/09 13:52
L653	5	"4322695".URPN.	USPAT	OR	ON	2005/11/09 13:52
L654	5	"5519363".URPN.	USPAT	OR	ON	2005/11/09 13:52
L655	10	("3179904" "3191055" "3459879" "4490690" "4703288" "5270672" "5426399" "5519363" "5634208" "5777526").PN.	USPAT	OR	ON	2005/11/09 13:52
L656	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:52
L657	9	("3351816" "3370184" "3560893" "3904997" "4379307" "4389429" "4575700" "4581291" "4673904").PN.	USPAT	OR	ON	2005/11/09 13:52
L658	15	"4379307".URPN.	USPAT	OR	ON	2005/11/09 13:52
L659	3	("4379307" "4499659" "4596070").PN.	USPAT	OR	ON	2005/11/09 13:52
L660	4	"5512776".URPN.	USPAT	OR	ON	2005/11/09 13:52
L661	6	("5012319" "5138436" "5280253" "5303419" "5471181" "5796321").PN.	USPAT	OR	ON	2005/11/09 13:52
L662	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:52
L663	4	"5012319".URPN.	USPAT	OR	ON	2005/11/09 13:53
L664	9	("4441088" "5012319" "5219827" "5404119" "5406233" "5426399" "5496795" "5616538" "5703020").PN.	USPAT	OR	ON	2005/11/09 13:53
L665	53	((("257"/\$.CCLS. AND TRANSMISSION ADJ LINE) AND OXIDE) AND (HOLE TRENCH GAP THROUGH VIA)) AND WAVE ADJ GUIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L666	10	"4554567".URPN.	USPAT	OR	ON	2005/11/09 13:53
L667	9	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND SILICON ADJ OXIDE	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L668	9	"4575700".URPN.	USPAT	OR	ON	2005/11/09 13:53
L669	3	("3891949" "3982271" "4379307").PN.	USPAT	OR	ON	2005/11/09 13:53
L670	2	"5426399".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L671	2	"20020149108".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L672	25	(L510 or L506 or L508 or L509 or L507) and transmission adj line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L673	2	"6756673".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L674	109	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L675	147	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L676	171	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L677	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L678	184	(((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L679	114	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L680	203	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L681	124	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/11/09 13:53
L682	194	gate with polysilicon with copper	USPAT	OR	ON	2005/11/09 13:53
L683	186	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:53
L684	144	trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:53
L685	195	trench with etch\$5 with commonly	USPAT	OR	ON	2005/11/09 13:53
L686	165	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L687	176	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L688	146	((((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L689	201	(((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L690	109	((438/627).CCLS.) and evaporation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L691	147	(438/42).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L692	171	(forbes and ahn and micron.as.) and signal and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L693	109	(369/194).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L694	184	((((438/687).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and conductive with line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L695	114	(isolation with trench and silicon with substrate and "438"/\$.ccls.) and waveguide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L696	203	((isolation with trench and silicon with substrate and "438"/\$.ccls.) and etch with substrate) and ground and signal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L697	124	waveguide and trench and barrier and oxide and copper	USPAT	OR	ON	2005/11/09 13:53
L698	194	gate with polysilicon with copper	USPAT	OR	ON	2005/11/09 13:53
L699	186	thermal with evaporation with CVD and "438"/\$.ccls.	USPAT	OR	ON	2005/11/09 13:53
L700	144	trench with etch\$5 with improve	USPAT	OR	ON	2005/11/09 13:53
L701	195	trench with etch\$5 with commonly	USPAT	OR	ON	2005/11/09 13:53
L702	165	(coplanar with line and "257"/\$.ccls.) and trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L703	176	((333/246).CCLS.) and coplanar	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L704	146	(((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L705	201	((((333/238).CCLS.) and waveguide) not (((333/246).CCLS.) and waveguide) not (((333/246).CCLS.) and coplanar))) not (((333/246).CCLS.) and waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L706	234	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L707	214	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L708	237	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L709	260	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L710	292	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L711	296	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L712	234	signal with line and ground with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L713	214	((438/31).CCLS.) and substrate with (trench hole via gap through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L714	237	(((((438/653).CCLS.) and substrate with (trench gap via cavity through hole)) and silicon with substrate) and barrier) and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L715	260	CoPlanar with Waveguide and "257"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L716	292	((333/1).CCLS.) not (((333/1).CCLS.) and coplanar)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L717	296	(kie with ahn).in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L718	318	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L719	322	signal with line and ground with line and 438/6\$2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L720	402	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L721	410	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L722	409	waveguide with trench	USPAT	OR	ON	2005/11/09 13:53
L723	318	((438/627).CCLS.) and silicide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L724	322	signal with line and ground with line and 438/6\$2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L725	402	(438/31).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 13:53
L726	410	(waveguide and "257"/\$.ccls.) and signal with ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L727	409	waveguide with trench	USPAT	OR	ON	2005/11/09 13:53
L728	440	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L729	440	coplanar with waveguide and silicon with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53

L730	537	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L731	537	(TRANSMISSION WITH LINE SAME WAVE ADJ GUIDE) AND (HOLE TRENCH GAP THROUGH VIA)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L732	701	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L733	701	coplanar with waveguide and "333"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:53
L734	996	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/11/09 13:53
L735	996	silicide with silicon with nitride and 438/6\$2.ccls.	USPAT	OR	ON	2005/11/09 13:54
L736	1079	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:54
L737	1079	waveguide with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:54
L738	1163	(coplanar and waveguide and signal and (trech hole thoughole))".clm"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:54
L739	45	(coplanar and waveguide and signal and (trech hole thoughole)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/09 13:54
L740	20	(coplanar and waveguide and signal and (trech hole thoughole)).clm.	US-PGPUB	OR	ON	2005/11/09 13:54
L741	31	(coplanar and waveguide and (trech hole thoughole)).clm.	US-PGPUB	OR	ON	2005/11/09 13:54
L742	77	(coplanar and waveguide and (trech hole thoughole via)).clm.	US-PGPUB	OR	ON	2005/11/09 13:54
L743	106	(coplanar and waveguide and (trech hole thoughole via channel)).clm.	US-PGPUB	OR	ON	2005/11/09 13:54
L744	29	L743 not L742	US-PGPUB	OR	ON	2005/11/09 13:54

L745	1744	(438/427).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/09 14:28
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